



Product Change Notification

Change Notification #: 116256 - 00
Change Title: Intel® Server System R2312WTTYSR
 PCN 116256-00, Product Design, Label,
 Add India BSMI RoHS mark on 1100W
 PSU, Sync-Rec mosfet new design
Date of Publication: May 07, 2018

Key Characteristics of the Change:
 Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	May 31, 2018
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the 1100W power supply integrated on the Intel® Server System R2312WTTYSR.

- India BSMI RoHS safety mark regulatory label on the 1100W power supply.
- Roll up the Product number from G84027-008 to G84027-009 due the improvement on the Sync-Rec mosfet.
- Product revision change from 02F to 03F

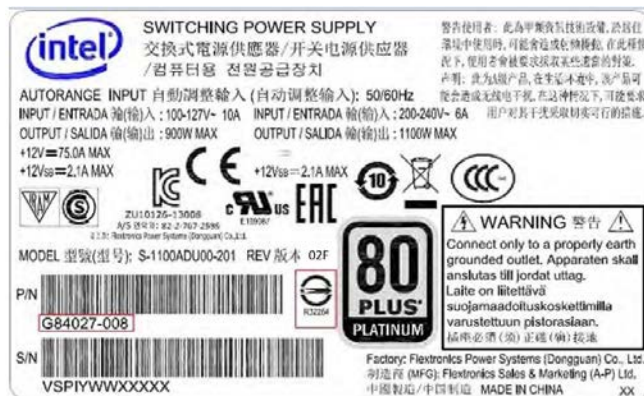


Image 1. Power supply label before change



Image 2. Power supply label after change

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2312WTTYSR	951229	J11495-012	J11495-013

PCN Revision History:

Date of Revision:

May 7, 2018

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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